

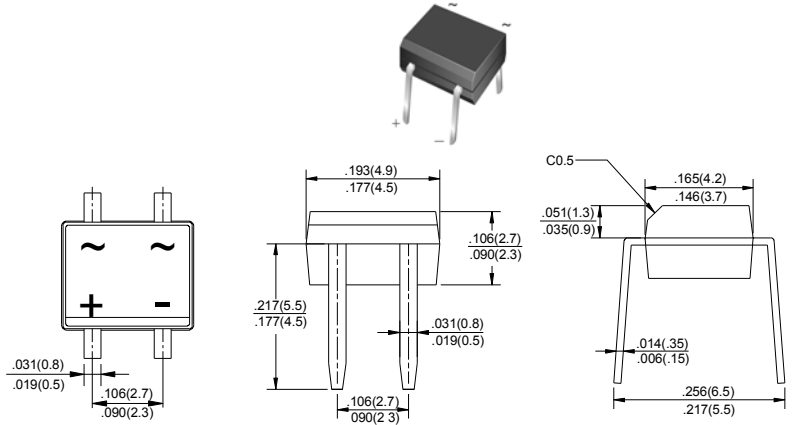
MB05M --- MB10M

FEATURES

- Rating to 1000V PRV
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique results in inexpensive product
- Lead tin plated copper

Mechanical Data

- Polarity:Symbol molded on body
- Mounting position :Any



MBM Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics (Ta=25 °C unless otherwise noted)

Characteristic	Symbo	MB05M	MB1M	MB2M	MB4M	MB6M	MB8M	MB10M	Unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current (Note 1) @TA=40 °C	$I_{(AV)}$	0.8							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave	I_{FSM}	30							A
Peak Forward Voltage at 0.8A DC	V_F	1.1							V
Maximum DC Reverse Current at Rated DC Bolcking Voltage @TJ=25°C @TJ=125°C	I_R	5.0							μA
Typical Junction Capacitance Per Element (Note2)	C_J	15							pF
Typical Thermal Resistance (Note3)	R_{JC}	75							°C/W
Operating Temperature Range	T_J	-55 to +150							°C
Storage Temperature Range	T_{STG}	-55 to +150							°C

NOTES: 1.Mounted on P.C. board. 2.Measured at1.0MHz and applied reverse voltage of 4.0V DC. 3.Thermal resistance junction to case.

MB05M --- MB10M CHARACTERISTIC CURVES

FIG.1-FORWARD CURRENT DERATING CURVE

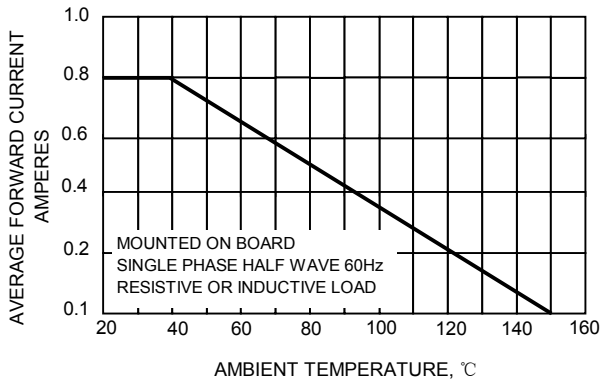


FIG.2-MAXIMUM NON-REPETITIVE SURGE CURRENT

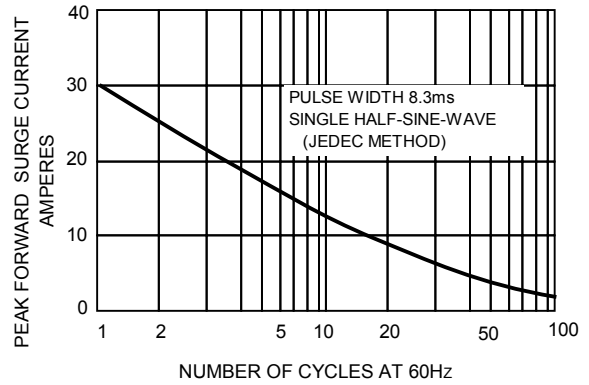


FIG.3-TYPICAL REVERSE CHARACTERISTICS

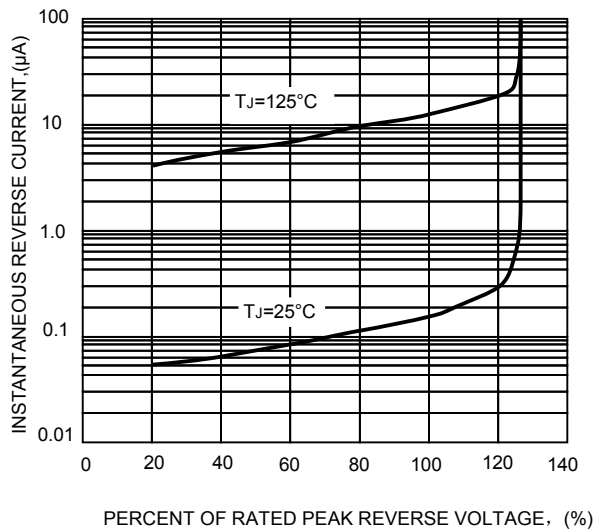


FIG.4-TYPICAL FORWARD CHARACTERISTICS

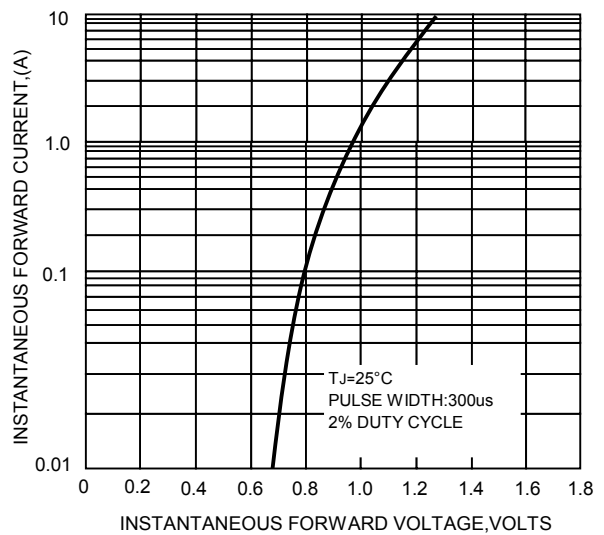


FIG.5-TYPICAL JUNCTION CAPACITANCE

